Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.012”**

**ANODE**

**.005 x .005**

**ANODE**

**.012”**

**Top Material: Al**

**Backside Material: AuAs**

**Bond Pad Size = .0051 x .0051”**

**Backside Potential: CATHODE**

**Mask Ref: 05**

**APPROVED BY: DK DIE SIZE .012” X .012” DATE: 1/11/23**

**MFG: SILICON SUPPLIES THICKNESS .007” P/N: 1N5711**

**DG 10.1.2**

#### Rev B, 7/1